

Sub  
C17  
B1  
1. (Once Amended) An interposer for electrically coupling a semiconductive device to an electrical apparatus, the interposer comprising:

an electrically insulative substrate having a portion that has a uniform thickness, said portion having a planar surface [comprised of an electrically insulating, ceramic material]; and  
an electrical conductor on the planar surface of the portion of the electrically insulative substrate, the electrical conductor having a receiving end on the planar surface of the portion of the electrically insulative substrate for connecting to a semiconductive device and a terminal end on the planar surface of the portion of the electrically insulative substrate for connecting to an electrical apparatus.

Sub  
D2  
2. (Once Amended) An interposer as recited in claim 1, wherein the substrate comprises crystalline glass [a substantially planar sheet].

4. (Unchanged) An interposer as recited in claim 1, wherein the receiving end protrudes upwardly with respect to the substrate.

B2  
6. (Once Amended) An interposer as recited in claim 1, wherein the substrate comprises a material selected from the group consisting of glass, alumina, glass ceramic, nonmetallic nitride, aluminum nitride, nonmetallic carbide, and mixtures [and derivatives] thereof.

Sub  
D3  
7. (Once Amended) An interposer as recited in claim 1, wherein the substrate comprises a [boron] nitride.

8. (Unchanged) An interposer as recited in claim 1, wherein the interposer further comprises an electrically insulating layer on a portion of the conductor between the receiving end and the terminal end.

D4  
33  
con x  
9. (Once Amended) An interposer as recited in claim [8]Z, wherein the nitride comprises boron nitride [electrically insulating layer comprises a thermally conductive material].

Sub  
C2  
10. (Once Amended) An interposer for electrically coupling a semiconductive device to an electrical apparatus, the interposer comprising

a [substantially homogeneous, substantially planar] sheet having a portion that has a uniform thickness, said sheet comprised of an electrically insulating, [inorganic ceramic] material; and

an electrical conductor on the [sheet] portion, the electrical conductor having a receiving end on said portion for connecting to a semiconductive device and a terminal end on said portion for connecting to an electrical apparatus, such that the semiconductive device is electrically coupled to the electrical apparatus when the semiconductive device is connected to the receiving end of the electrical conductor and the terminal end of the electrical conductor is connected to the electrical apparatus.

Sub  
De  
11. (Once Amended) An interposer as recited in claim 10, wherein the material comprises [substrate consists essentially of] alumina.

D4 12. (Once Amended) An interposer as recited in claim 10, wherein the material comprises [substrate consists essentially of a] crystallized glass [ceramic material].

B3  
Sub  
C3 13. (Once Amended) An interposer for electrically coupling a semiconductive device to an electrical apparatus, the interposer comprising:

an electrically insulative [substantially homogeneous, substantially planar] sheet having a portion that has a uniform thickness, said portion being composed of a[n electrically insulating] material selected from the group consisting of [glass ceramics,] devitrified ceramics, vitro ceramics, [alumina,] single oxide ceramics, and mixed oxide ceramics, and mixtures [and derivatives] thereof, and

an electrical conductor on said portion [the sheet], the electrical conductor having a receiving end on said portion for connecting to a semiconductive device and a terminal end on said portion for connecting to an electrical apparatus, such that the semiconductive device is electrically coupled to the electrical apparatus when the semiconductive device is connected to the receiving end of the electrical conductor and the terminal end of the electrical conductor is connected to the electrical apparatus.

14. (Once Amended) An interposer for electrically coupling a semiconductive device to an electrical apparatus, the interposer comprising:

B3  
C3  
an electrically insulative [substantially homogeneous, substantially planar] sheet having a portion that has a uniform thickness, said portion being composed of an electrically insulating material selected from the group consisting of alumina, alumina with silica, alumina with silicates, alumina with derivatives of silicates, and mixtures [and derivatives] thereof; and

an electrical conductor on said portion [the sheet], the electrical conductor having a receiving end on said portion for connecting to a semiconductive device and a terminal end on said portion for connecting to an electrical apparatus, such that the semiconductive device is electrically coupled to the electrical apparatus when the semiconductive device is connected to the receiving end of the electrical conductor and the terminal end of the electrical conductor is connected to the electrical apparatus.

Amended  
C3  
B3  
End

15. (Once Amended) An interposer for electrically coupling a semiconductive device to an electrical apparatus, the interposer comprising:

an electrically insulative [substantially homogeneous, substantially planar] sheet having a portion that has a uniform thickness, said portion being composed of an electrically insulating material selected from the group consisting of boron nitrides, aluminum nitrides, and mixtures [and derivatives] thereof; and

an electrical conductor on said portion [the sheet], the electrical conductor having a receiving end on said portion for connecting to a semiconductive device and a terminal end on said portion for connecting to an electrical apparatus, such that the semiconductive device is electrically coupled to the electrical apparatus when the semiconductive device is connected to the receiving end of the electrical conductor and the terminal end of the electrical conductor is connected to the electrical apparatus.

✓  
Add new Claims 19-28 as follows:

39  
19. (New)  
nonmetallic nitride.

An interposer as recited in claim 7, wherein the nitride comprises

B4  
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20. (New)  
carbide.

An interposer as recited in claim 1, wherein the substrate comprises a

Full  
1-20  
41  
21. (New)  
nonmetallic carbide.

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An interposer as recited in claim 20, wherein the carbide comprises

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~~22.~~ (New) The interposer as defined in Claim 13, wherein:

the portion of the sheet has a planar surface;  
the electrical conductor is on the planar surface of the portion of the sheet;  
the receiving end is on the planar surface of the portion of the sheet; and  
the terminal end is on the planar surface of the portion of the sheet.

43

~~23.~~ (New) The interposer as defined in Claim 14, wherein:

the portion of the sheet has a planar surface;  
the electrical conductor is on the planar surface of the portion of the sheet;  
the receiving end is on the planar surface of the portion of the sheet; and  
the terminal end is on the planar surface of the portion of the sheet.

44

~~24.~~ (New) The interposer as defined in Claim 15, wherein:

the portion of the sheet has a planar surface;  
the electrical conductor is on the planar surface of the portion of the sheet;  
the receiving end is on the planar surface of the portion of the sheet; and  
the terminal end is on the planar surface of the portion of the sheet.

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~~25.~~ (New) An interposer for electrically coupling a semiconductor device to an electrical apparatus, the interposer comprising:

an electrically insulative substrate comprised of a material selected from the group consisting of crystalline glass, nitride, and carbide, and mixtures thereof; and

an electrical conductor on the substrate, the electrical conductor having a receiving end for connecting to a semiconductor device and a terminal end for connecting to an electrical apparatus.

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~~26.~~ (New) The interposer as defined in Claim ~~25~~, wherein the nitride is a nonmetallic nitride.

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~~27.~~ (New) The interposer as defined in Claim ~~25~~, wherein the nonmetallic nitride is boron nitride.

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~~28.~~ (New) The interposer as defined in Claim ~~25~~, wherein the carbide is a nonmetallic carbide.